

# MURD2020CT

Rev.F May.-2016

## / Descriptions

TO-252

Ultrafast Recovery Diode in a TO-252 Plastic Package.

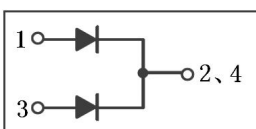
## / Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

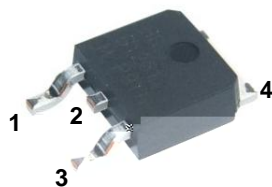
## / Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode.

## / Equivalent Circuit



## / Pinning



PIN1 Anode

PIN 2 4 Cathode

PIN 3 Anode

## / $h_{FE}$ Classifications & Marking

See Marking Instructions.

**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	200	V
RMS Reverse Voltage	$V_{RMS}$	140	V
DC Blocking Voltage	$V_{DC}$	200	V
Average Forward Current	$I_F$	2× 10	A
Non Repetitive Peak Surge Current	$I_{FSM}$	120	A
Thermal Resistance Junction to Case	$R_{Jc}$	2.8	/W
Operating and Storage Temperature Range	$T_j$ $T_{stg}$	-55 150	

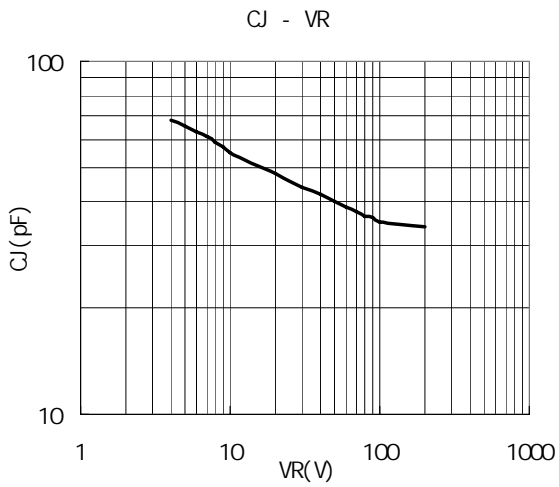
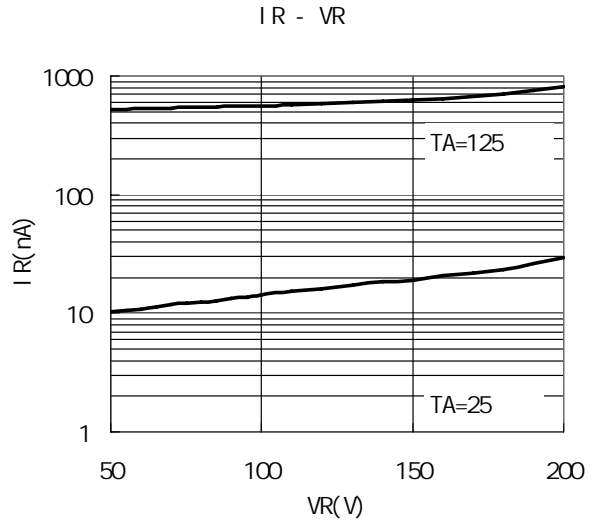
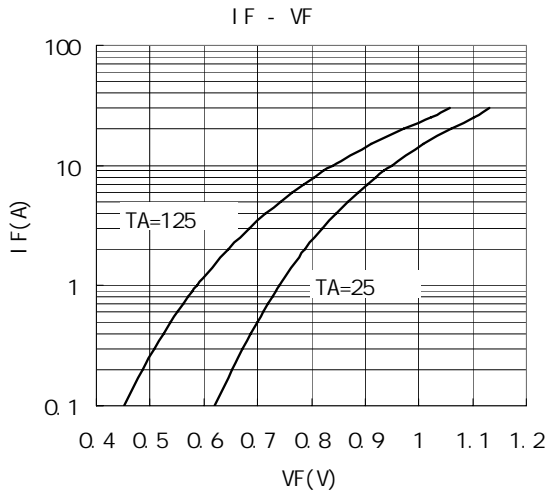
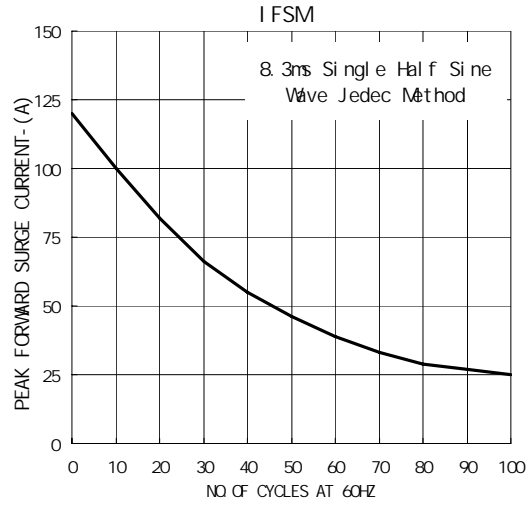
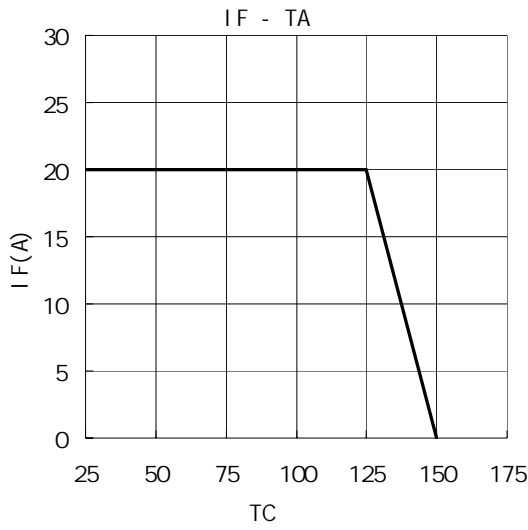
**/ Electrical Characteristics(Ta=25 )**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	$V_F$	$I_F=2A$ $T_c=25$		0.79		V
		$I_F=2A$ $T_c=125$		0.65		V
		$I_F=10A$ $T_c=25$		0.95	1.0	V
		$I_F=10A$ $T_c=125$		0.84	0.9	V
Instantaneous Reverse Current	$I_R$ Note 1	$V_R=200V$ $T_a=25$			10	A
		$V_R=200V$ $T_a=125$			150	A
Reverse Recovery Time	$t_{rr}$	$I_F=0.5A$ $I_R=1.0A$ $I_{RR}=0.25A$			35	ns

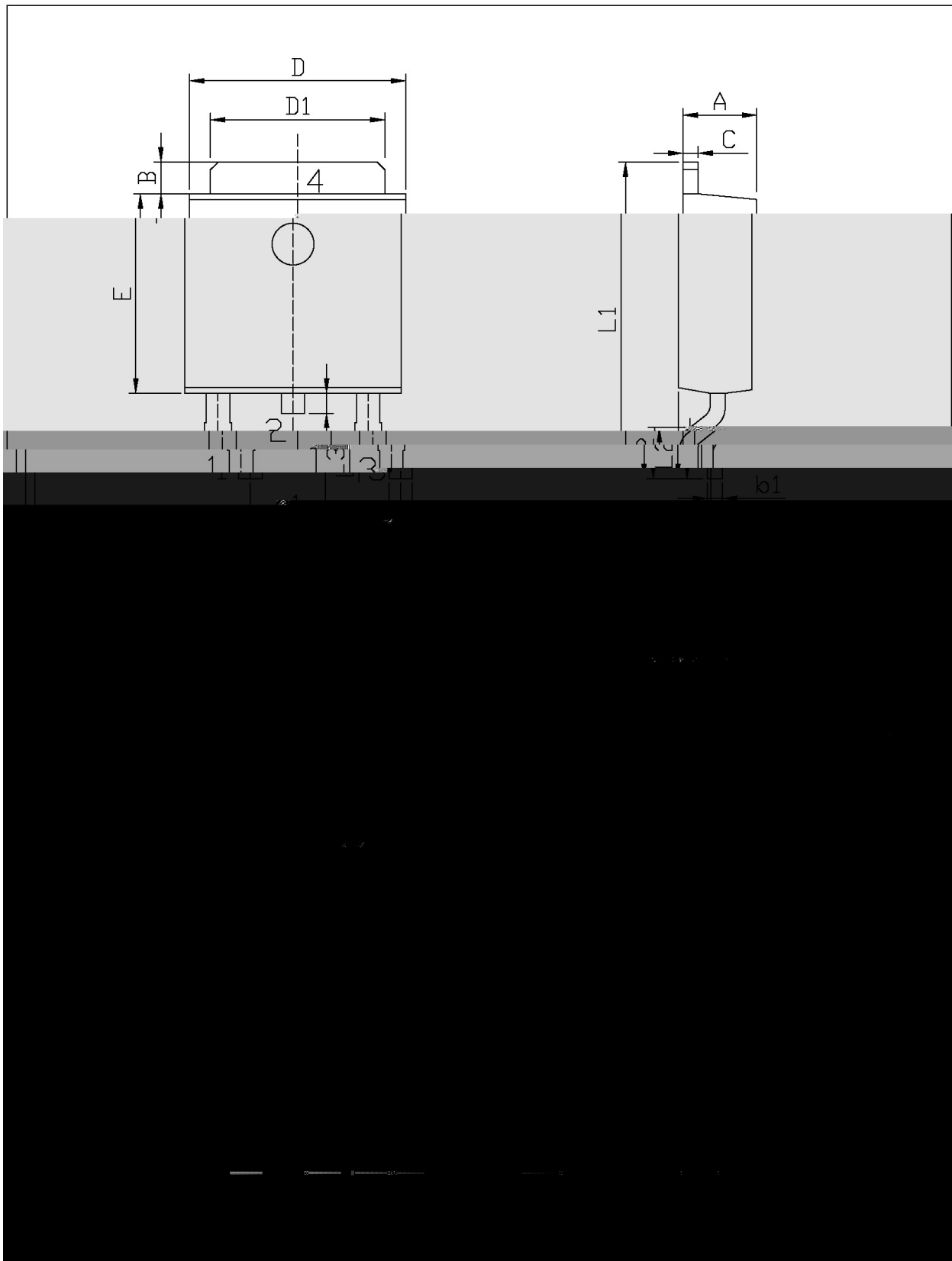
/Notes

1. /Short duration pulse test used to minimize self-heating effect.
2. / Unless otherwise noted, values for the parameters of a single chip

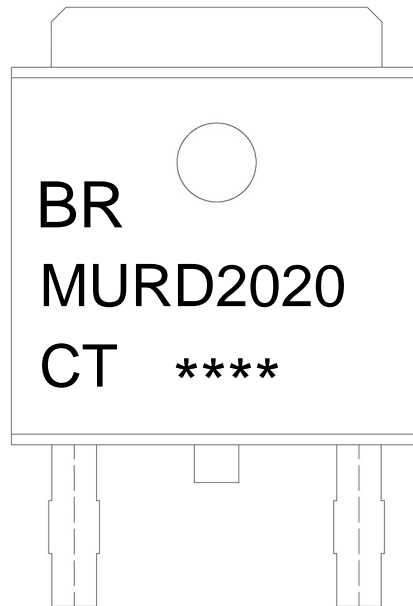
**/ Electrical Characteristic Curve**



/ Package Dimensions



/ Marking Instructions



BR

MURD2020

CT:

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Note:

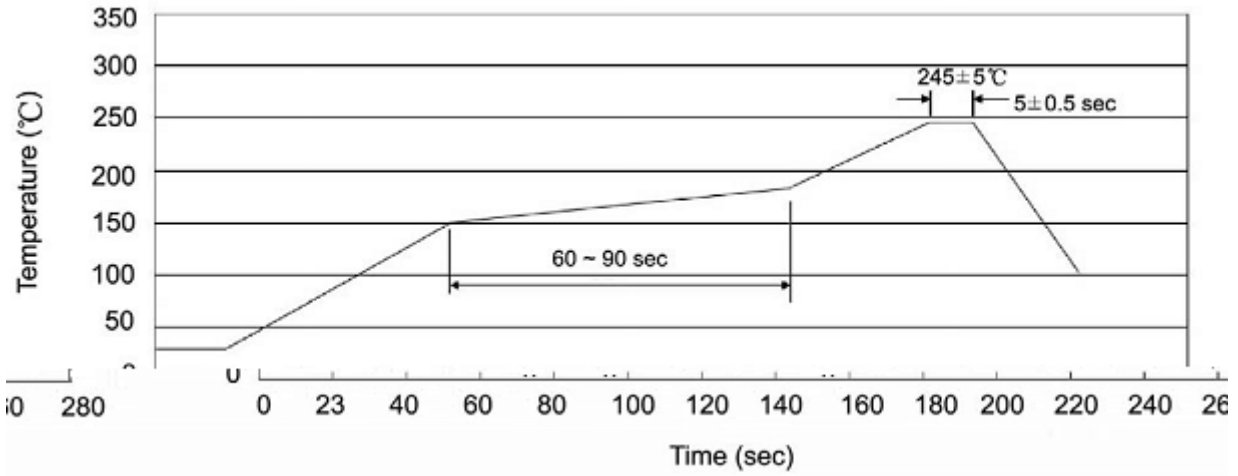
BR: Company Code

MURD2020 Product Type.

CT: Internal Structure

\*\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1            25   150            60   90sec;            1.Preheating:25~150 , Time:60~90sec.
- 2            245±5                    5±0.5sec;            2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3                            2   10 /sec.            3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5                    10±1 sec.                    Temp.:260±5                    Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	5	25,000	13 ×16	360×360×50	385×257×392

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

/ Notices